



Standard Temp.

Wide Temp.

S750-3A | mSATA SSD



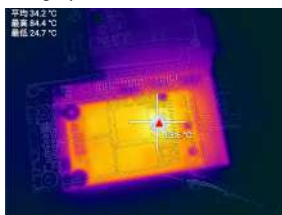
United States Patent / US11051392B2
Taiwan Invention Patent / I703921
China Utility Patent / CN 211019739 U

S750-3A uses industrial durable 3D TLC chip to achieve a significant improvement against other standard, consumer 3D TLC chips in system performance and product durability. The SSD is also equipped with a cache DRAM that offers cache/buffer function for improved SSD performance and service life.

Main Feature

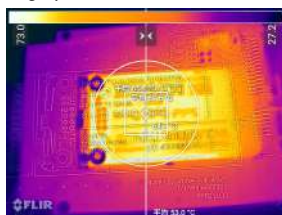
- Industrial, high specification, and durable 3D TLC
- Equipped with a cache DRAM
- Supports error correction codes (ECC) such as LDPC
- Global Wear Leveling technology
- Supports S.M.A.R.T. function (exclusive smart tool software developed by TEAMGROUP)
- End-to-end data protection
- Supports TRIM commands
- Supports TCG Opal 2.0 (WT series)
- Supports AES 256-bit hardware encryption (WT series)
- Patented graphene/copper cooling technology (WT series)
United States Patent (No.: US11051392B2)
Taiwan Invention Patent (No.: I703921)
China Utility Model Patent (No.: CN 211019739 U)

W/O graphene heat sink



Heat is concentrated in the controller, which can easily cause the SSD to slow down or crash.

W/graphene heat sink



The heat is evenly dispersed on the graphene heat sink to maintain the normal operation of the SSD.

Specification

Interface	SATA III 6.0Gb/s
Flash Type	3D TLC
Capacity	128GB / 256GB / 512GB / 1TB
Sequential R/W	R/W: 560 / 510MB/s (Max.)
Max. Power consumption	3.3V x 495mA (operation)
Dimension	50.80(L) x 29.85(W) x 3.86(H) mm
Shock	<ul style="list-style-type: none"> • Operation: 50G / 11ms (compliant with MIL-STD-202G Test condition A) • Non-operation: 1,500G / 0.5ms (compliant with MIL-STD-883K Test condition B)
Vibration	<ul style="list-style-type: none"> • Operation: 7.69 Grms, 20~2,000 Hz / random (compliant with MIL-STD-810G General) • Non-operation: 4.02 Grms, 15 ~ 2,000 Hz / sine (compliant with MIL-STD-810G General)
MTBF	> 3 million hours
Storage Temperature	-55°C (-67°F) ~ +95°C (203°F)
Operation Temperature	<ul style="list-style-type: none"> • Standard Temp.: 0°C (32°F) ~ +70°C (158°F) • Wide Temp.: -40°C (-40°F) ~ +85°C (185°F)
P/E Cycle	3K for W.T / 10K for S.T
Thermal Sensor	✓
External DRAM Buffer	✓
TRIM	✓
S.M.A.R.T.	✓
Warranty	3-year limited warranty

[1] Transmission speed varies depending on your system performance (i.e. software, hardware, use, product capacity, etc.)

[2] Work load used for assessing DWPD may vary from your actual operational environment (i.e. software, hardware, use, product capacity, etc.).

※We reserve the right to modify product specifications without prior notice.

Ordering Information

S750-3A	Capacity	Team P/N
Standard Temp.	128GB	TE128GS750MB30
	256GB	TE256GS750MB30
	512GB	TE512GS750MB30
	1TB	TE1TS750MB30
Wide Temp.	128GB	TE128GS750MB30-W
	256GB	TE256GS750MB30-W
	512GB	TE512GS750MB30-W
	1TB	TE1TS750MB30-W



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